Integrated Device Technology, Inc.
6024 Silver Creek Valley Road
San Jose, CA 96138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **W1107-01** DATE: **July 5, 2011**

Product Affected: Refer Attachment 3

Date Effective: **October 5, 2011**

MEANS OF DISTINGUISHING CHANGED DEVICES:

- ■ Product Mark Assembly lot# and Date Code
- ☐ Back Mark
- ☐ Date Code
- ☐ Other

Contact: Bimla Paul
Title: Product Quality Assurance
Phone #: (408) 574-6419
Fax #: (408) 284-8362
E-mail: Bimla.Paul@idt.com

Attachment: ■ Yes ☐ No

Samples: Please contact your local IDT sales representative

DESCRIPTION AND PURPOSE OF CHANGE:

- ☐ Die Technology
- ☐ Wafer Fabrication Process
- ☐ Assembly Process
- ☐ Equipment
- ☐ Material
- ☐ Testing
- ■ Manufacturing Site
- ☐ Data Sheet
- ☐ Other

This notification is to advise our customers that IDT is in the process of transferring the wafer Fab production of the attached list of products currently manufactured in the IDT Hillsboro, Oregon (Fab4) to Taiwan Semiconductor Manufacturing Corporation (TSMC).

There is no expected change to the data sheet, package or backend manufacturing process.

Production at IDT Hillsboro, Oregon (Fab 4) is expected to continue through August 2011.

RELIABILITY/QUALIFICATION SUMMARY:

Wafer and Component level Qualification and Characterization tests will verify that there is no change to the performance or reliability of the product. please refer to Attachment 2 for sample qualification reports.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____ ☐ ***Approval for shipments prior to effective date.***

Name/Date: _____ E-Mail Address: _____

Title: _____ Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____

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PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT 1 - PCN # : W1107-01

PCN Type: Wafer Fab Manufacturing Site Change - IDT Fab 4 to TSMC

Data Sheet Change: None

Detail Of Change:

This notification is to advise our customers that IDT is in the process of transferring the wafer Fab production of the attached list of products currently manufactured in the IDT Hillsboro, Oregon (Fab4) to Taiwan Semiconductor Manufacturing Corporation (TSMC).

There is no expected change to the data sheet, package or backend manufacturing process.

Production at IDT Hillsboro, Oregon (Fab 4) is expected to continue through August 2011.

Samples may not be available for all products on the list unless specifically requested in advance. Please contact your IDT sales representative to request samples or additional information.

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PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT 2 - PCN # : W1107-01

TSMC Transfer Qualification Test Result Summary

Technology Information: 0.18 µm **Fab Location: TSMC Fab 8**

Technology Qualification Vehicle Test Summary – JESD47 Recommended Tests

Test / Conditions	Lead Vehicle: 9LPRS387
	Sample Size / Rejects/ each lot
High Temperature Operating Life (Dynamic) JESD22-A108B, +125°C @ 1000 hours or equivalent	77/ 0 77 / 0 77 / 0
Temperature Cycle JESD22-A104B, -55°C -/125°C, 1000 cycles	45 / 0 45 / 0 45 / 0
High Temperature Storage Bake JESD22-A-103-B, 150°C, 1000 hrs	77 / 0 77 / 0 77 / 0
ESD: Human Body Model JESD22-A114F	5 / 0
ESD: Charged Device Model JEDEC 22-101C	5 / 0
ESD: Machine Model JESD22-A115B	5 / 0
Latch-up JESD78B	6 / 0
Electrical Characterization per Datasheet conditions	10

Technology Qualification Vehicle Test Summary – Supplemental Tests

Test / Conditions	Lead Vehicle: 9LPRS387
	Sample Size / Rejects/ each lot
Ball Shear Test JESD22-B116-A, Ball Shear Strength > 5.7g	5 / 0 5 / 0 5 / 0
Highly Accelerated Stress Test (HAST) EIA/JESD22-A110B, 130°C/85%R.H. Vcc max for 100 hours.	45 / 0 45 / 0 45 / 0
Autoclave EIA/JESD22-A102C, 168hrs @ 2 ATM, Saturated Steam @ 121°C	25 / 0 25 / 0 25 / 0

Note: For HAST, Autoclave and Temperature Cycle, samples have been subjected to pre-conditioning per JESD22-A113

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PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT 2 - PCN # : W1107-01

TSMC Transfer Qualification Test Result Summary

Technology Information: 0.35 µm **Fab Location: TSMC Fab 3**

Technology Qualification Vehicle Test Summary – JESD47 Recommended Tests

Test / Conditions	Lead Vehicle: 1493DG-18 Sample Size / Rejects/ each lot
High Temperature Operating Life (Dynamic) JESD22-A108B, +125°C @ 1000 hours or equivalent	77 / 0 77 / 0 77 / 0
Temperature Cycle JESD22-A104B, -55°C -/125°C, 1000 cycles	45 / 0 45 / 0 45 / 0
High Temperature Storage Bake JESD22-A-103-B, 150°C, 1000 hrs	77 / 0 77 / 0 77 / 0
ESD: Human Body Model JESD22-A114F	5 / 0
ESD: Charged Device Model JEDEC 22-101C	5 / 0
ESD: Machine Model JESD22-A115B	5 / 0
Latch-up JESD78B	6 / 0
Electrical Characterization per Datasheet conditions	10

Technology Qualification Vehicle Test Summary – Supplemental Tests

Test / Conditions	Lead Vehicle: 1493DG-18 Sample Size / Rejects/ each lot
Ball Shear Test JESD22-B116-A, Ball Shear Strength > 5.7g	5 / 0 5 / 0 5 / 0
Highly Accelerated Stress Test (HAST) EIA/JESD22-A110B, 130°C/85%R.H. Vcc max for 100 hours.	45 / 0 45 / 0 45 / 0
Autoclave EIA/JESD22-A102C, 168hrs @ 2 ATM, Saturated Steam @ 121°C	25 / 0 25 / 0 25 / 0

Note: For HAST, Autoclave and Temperature Cycle, samples have been subjected to pre-conditioning per JESD22-A113

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ATTACHMENT 3 - PCN # : W1107-01

IDT Part No	IDT Part No	IDT Part No	IDT Part No
9EMS9633BKILF	9UMS9001AKLF	9UMS9633BKILF	9VRS4883AKLF
9EMS9633BKILFT	9UMS9001AKLFT	9UMS9633BKILFT	9VRS4883AKLFT
9EMS9633BKLF	9UMS9610BKLF	9UMS9633BKLF	CV183-2APAG
9EMS9633BKLFT	9UMS9610BKLFT	9UMS9633BKLFT	CV183-2APAG8
9LVRS395CKLF	9UMS9610CKLF	9VRS4808AGLF	CV183-2BPAG
9LVRS395CKLFT	9UMS9610CKLFT	9VRS4808AGLFT	CV183-2BPAG8
9UM709BGILF	9UMS9633BFILF	9VRS4813AKLF	CV184-2APAG
9UM709BGILFT	9UMS9633BFILFT	9VRS4813AKLFT	CV184-2APAG8
9UM709BGLF	9UMS9633BFW3LF	9VRS4818AKLF	CV186-2APAG
9UM709BGLFT	9UMS9633BFW3LFT	9VRS4818AKLFT	CV186-2APAG8